

ABSTRACT

The present invention provides a method for producing a bonding composition containing copper particles and a second liquid medium. In this production method, the copper particles are produced in a first liquid medium using a wet reduction method, and thus a dispersion of the copper particles is prepared. Subsequently, the first liquid medium in the dispersion is ultimately, finally or eventually replaced with the second liquid medium while the dispersion is kept wet. It is also preferable that the first liquid medium is replaced with another liquid medium one or more times, and the second liquid medium is used in the final replacement. The liquid media are preferably replaced at a temperature of lower than 100°C. The second liquid medium preferably includes one or more of water, alcohol, ketone, ester, ether, and hydrocarbon.